

ABSTRACT

The occurrence of an undesirable phenomenon of a surface resin in a resin molding caused for example by peeling of a thin surface film of the resin molding is suppressed by subjecting the resin molding to a simple additional process. A resin molding heat-treating apparatus according to the present invention is for heat-treating partially at a high temperature a parting line portion W1 of a resin molding W or a specific portion of the resin molding W which portion is apt to undergo peeling of a thin surface resin film, the apparatus comprising a heating section 2 of a shape conforming to a contour line of a portion to be heated of the resin molding W and a fixing jig 4 for fixing the resin molding W removably, the portion to be heated of the resin molding W being heat-treated at a high temperature while being approximated to the heating section 2.